



Session Title:	[ThA2] Cleaning Challenges for the Next Generation Devices
Session Date:	November 14 (Thu.), 2024
Session Time:	10:50-12:25
Session Room:	Room A (Capri Room, 2F, Paradise Hotel Busan)
Session Chair:	Prof. Sangwoo Lim (Yonsei Univ., Korea)

[ThA2-1] [Invited] 10:50-11:15

Study on Bubbles in Wafer Clean System

KwangWook Lee, Heehwan Kim, Buyoung Jung, Judong Lee, KyoungHyeon Kim, and GilHyeon Choi (SEMES, Korea)

[ThA2-2] [Invited] 11:15-11:40

Introduction to Two-Phase Flow Analysis Techniques for Fluid Dynamic Analysis of Cleaning Processes: Volume of Fluid, Level Set, and Volume of Fluid - Level Set Coupling Methods

Dang Khoi Le (Seoul Nat'l Univ. of Science and Tech., Korea) and Ho Jun Kim (Hanyang Univ., Korea)

[ThA2-3] [Invited] 11:40-12:05

Preparation and Characterization of High Purity Colloidal Silica Abrasives for CMP Slurry

Tae-Dong Kim (Hannam Univ., Korea)

[ThA2-4] 12:05-12:25

Study on Scratch Generation during Copper Post-CMP Brush Cleaning for Sub_10nm Semiconductor Manufacturing Devices

Maheepal Yadav, Sanjay Bisht, Se-Hoon Park, Tae-Gon Kim, and Jin-Goo Park (Hanyang Univ., Korea)